

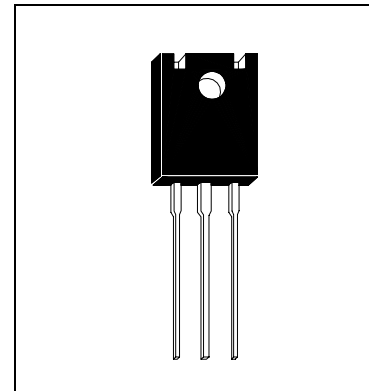


H2N6718V

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The H2N6718V is designed for general purpose medium power amplifier and switching.



Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C)..... 1.6 W
- Maximum Voltages and Currents
BVCBO Collector to Base Voltage 100 V
BVCEO Collector to Emitter Voltage 100 V
BVEBO Emitter to Base Voltage 5 V
IC Collector Current 1 A

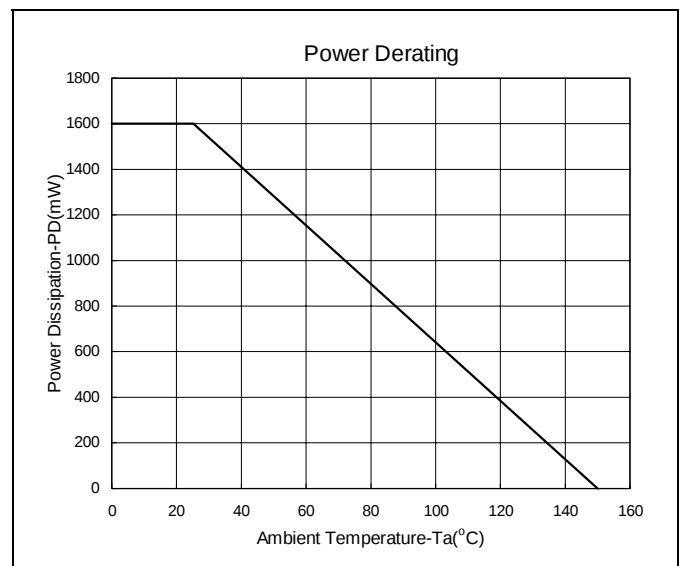
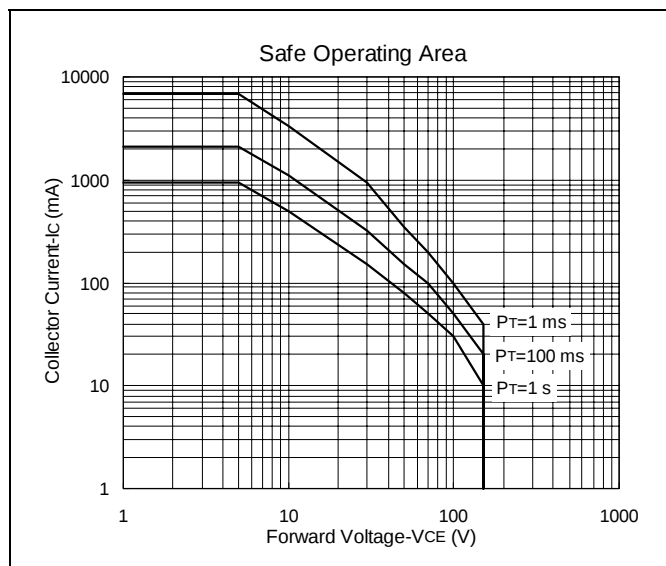
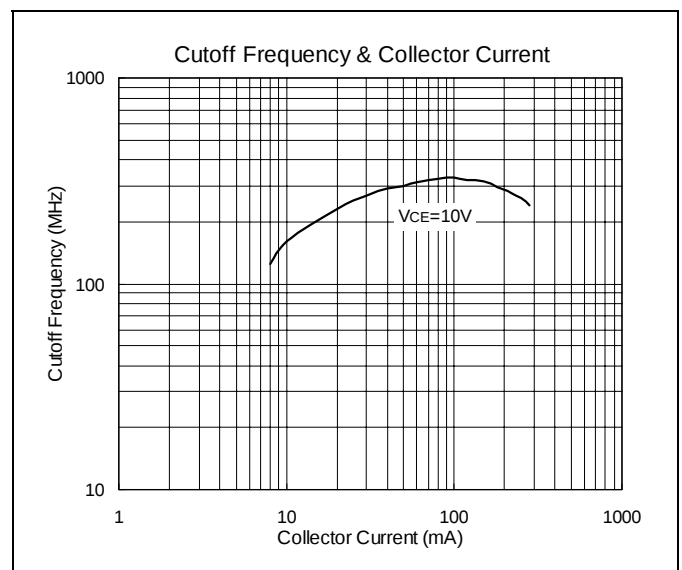
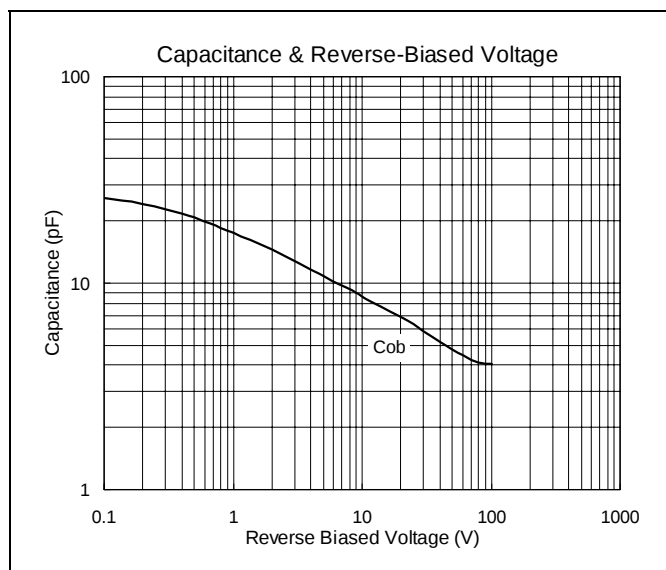
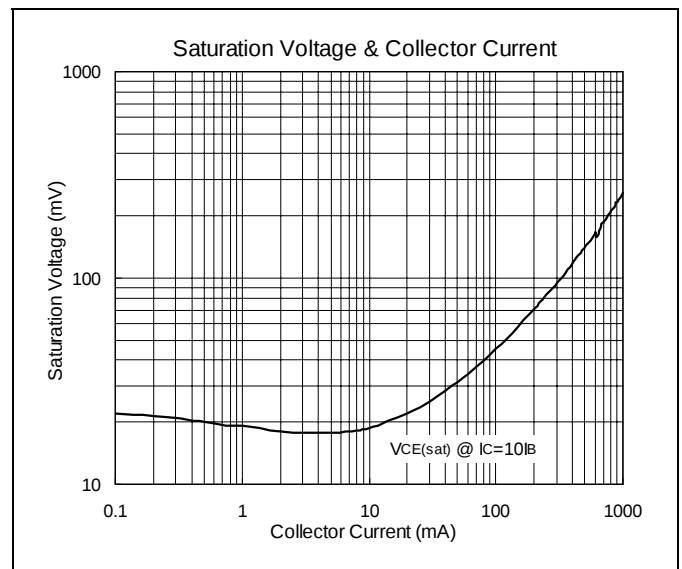
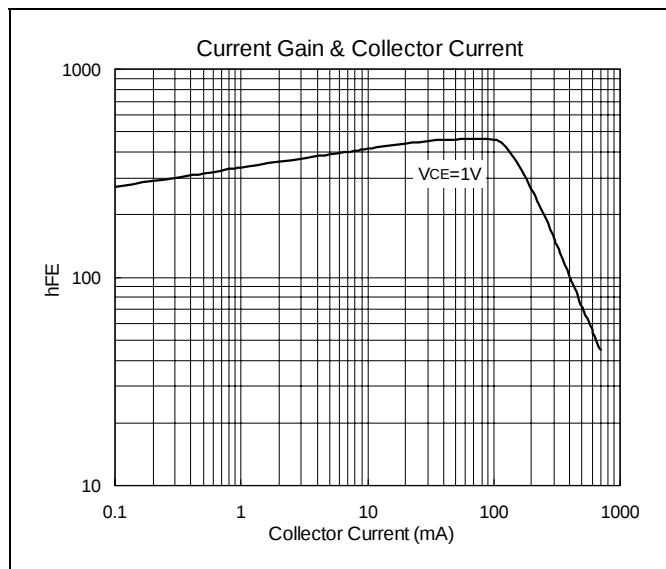
Electrical Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	100	-	-	V	IC=100uA, IE=0
BVCEO	100	-	-	V	IC=1mA, IB=0
BVEBO	5	-	-	V	IE=10uA, IC=0
ICBO	-	-	100	nA	VCB=80V, IE=0
*VCE(sat)	-	-	350	mV	IC=350mA, IB=35mA
*hFE1	80	-	-		IC=50mA, VCE=1V
*hFE2	50	-	250		IC=250mA, VCE=1V
*hFE3	20	-	-		IC=500mA, VCE=1V
fT	50	-	-	MHz	VCE=10V, IC=50mA, f=100MHz
Cob	-	-	20	pF	VCB=10V, f=1MHz, IE=0

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

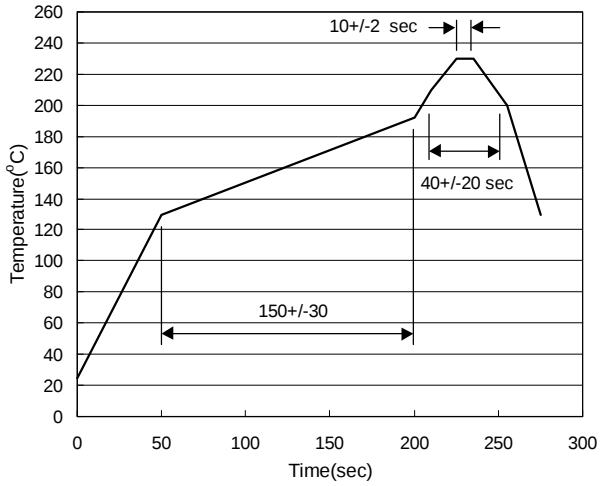


Characteristics Curve

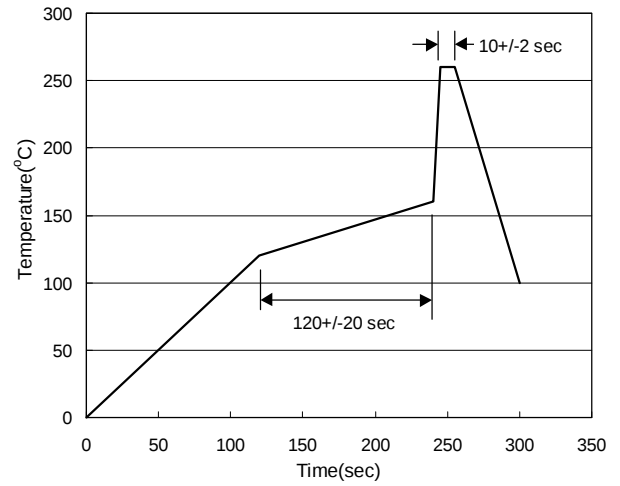




IR Reflow Profile

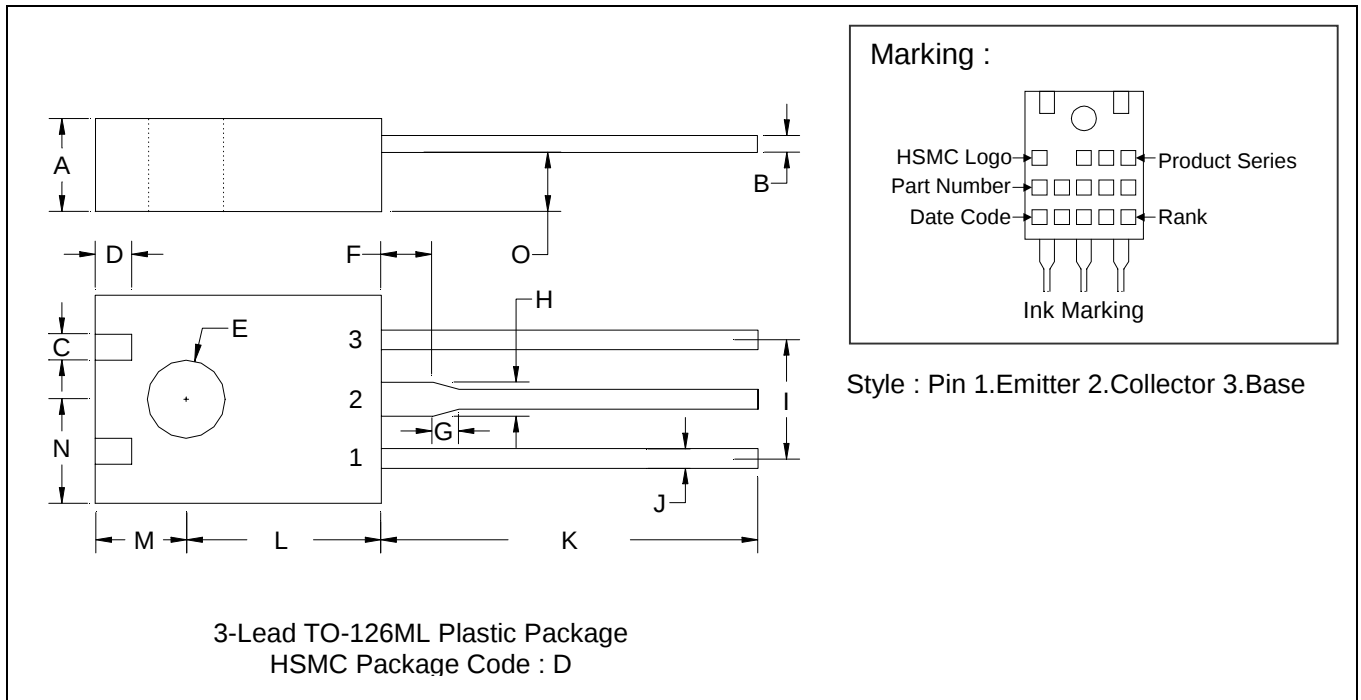


Temperature Profile for Dip Soldering





TO-126ML Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1356	0.1457	3.44	3.70	I	-	*0.1795	-	*4.56
B	0.0170	0.0272	0.43	0.69	J	0.0268	0.0331	0.68	0.84
C	0.0344	0.0444	0.87	1.12	K	0.5512	0.5906	14.00	15.00
D	0.0501	0.0601	1.27	1.52	L	0.2903	0.3003	7.37	7.62
E	0.1131	0.1231	2.87	3.12	M	0.1378	0.1478	3.50	3.75
F	0.0737	0.0837	1.87	2.12	N	0.1525	0.1625	3.87	4.12
G	0.0294	0.0494	0.74	1.25	O	0.0740	0.0842	1.88	2.14
H	0.0462	0.0562	1.17	1.42					

Notes : 1.Dimension and tolerance based on our Spec. dated Mar. 6,1995.
2.Controlling dimension : millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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